



## Product Change Notification / ALAN-28BFQE464

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**Date:**

17-May-2022

**Product Category:**

Switching Regulators

**PCN Type:**

Manufacturing Change

**Notification Subject:**

CCB 5102 Initial Notice: Qualification of CARC as new assembly site for LX7167ACLD-TR and LX7167CLD-TR catalog part numbers (CPN) available in 8L WDFN (2x2x0.8mm) package.

**Affected CPNs:**

[ALAN-28BFQE464\\_Affected\\_CPN\\_05172022.pdf](#)  
[ALAN-28BFQE464\\_Affected\\_CPN\\_05172022.csv](#)

**Notification Text:**

**PCN Status:**Initial Notification

**PCN Type:**Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section.  
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of CARC as new assembly site for LX7167ACLD-TR and LX7167CLD-TR catalog part numbers (CPN) available in 8L WDFN (2x2x0.8mm) package.

**Pre and Post Change Summary:**

	Pre Change	Post Change
Assembly Site	UTAC Dongguan	Carsem (Suzhou)



**Method to Identify Change:**Traceability code

**Qualification Plan:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

**Revision History:**May 17, 2022: Issued initial notice.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## **Attachments:**

[PCNALAN-28BFQE464 Qual Plan.pdf](#)

[PCNALAN-28BFQE464\\_Pre and Post Change\\_Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

## **Terms and Conditions:**

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

# CCB 5102

## Pre and Post Change Summary

### PCN# ALAN-28BFQE464



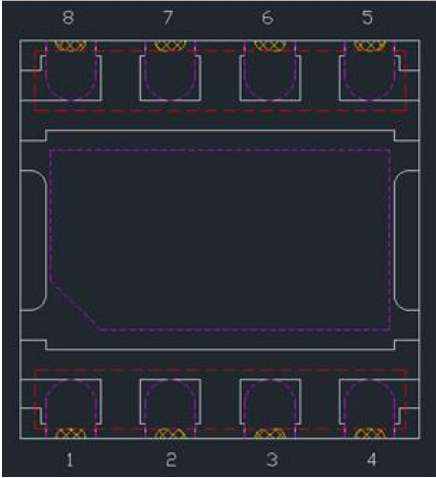
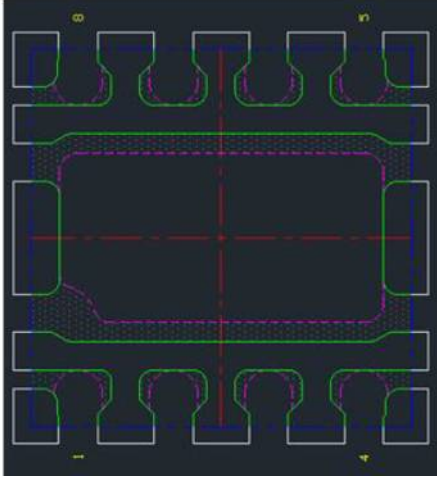
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# Pre and Post Change Summary

ASAC (UDG)	CARC																
																	
<table><tr><td>Material</td><td>C194 FH</td></tr><tr><td>Paddle Size</td><td>43 x 69 mil</td></tr><tr><td>DAP Surface Prep</td><td>Ag</td></tr><tr><td>Lead-lock</td><td>No</td></tr></table>	Material	C194 FH	Paddle Size	43 x 69 mil	DAP Surface Prep	Ag	Lead-lock	No	<table><tr><td>Material</td><td>C194</td></tr><tr><td>Paddle Size</td><td>43 x 67 mil</td></tr><tr><td>DAP Surface Prep</td><td>Spot Ag</td></tr><tr><td>Lead-lock</td><td>Half-etched</td></tr></table>	Material	C194	Paddle Size	43 x 67 mil	DAP Surface Prep	Spot Ag	Lead-lock	Half-etched
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## **QUALIFICATION PLAN SUMMARY**

**PCN# ALAN-28BFQE464**

**Date:  
April 28, 2022**

**Qualification of CARC as new assembly site for LX7167ACLD-TR and LX7167CLD-TR catalog part numbers (CPN) available in 8L WDFN (2x2x0.8mm) package.**

<u>Misc.</u>	Assembly site	CARC
	BD Number	BD-000623 rev01
	MP Code (MPC)	U0131QNYCA01
	Part Number (CPN)	LX7167ACLD-TR
	MSL information	MSL-1@260C
	Assembly Shipping Media (T/R, Tube/Tray)	Cannister (Final shipment is T/R)
	Base Quantity Multiple (BQM)	3,000
	Reliability Site	MTAI
	CCB#	5102
<u>Lead-Frame</u>	Paddle size	43 x 67 mil
	Material	C194
	DAP Surface Prep	Spot Ag
	Treatment	None
	Process (Stamped/Etched)	Etched
	Lead-lock Design (Locking Hole, Half Etched, Dimple, etc.)	Half Etched
	Part Number	441959ASMC
	Lead frame Thickness	8 mils
	Lead Plating	Matte Tin
	Strip Size	240x75mm
	Strip Density	2,376 units
<u>Bond Wire</u>	Material	CuPdAu
<u>Die Attach</u>	Part Number	QMI519
	Conductive	Yes
<u>MC</u>	Part Number	G770HCD
<u>PKG</u>	PKG Type	WDFN
	Pin/Ball Count	8
	PKG width/size	2x2x0.8mm

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	REL Test Site	Special Instructions
Standard Pb-free Solderability	J-STD-002D ; Perform 8 hour steam aging for Matte tin finish and 1 hour steam aging for NiPdAu finish prior to testing.  Standard Pb-free: Matte tin/ NiPdAu finish, SAC solder, wetting temp 245°C for both SMD & through hole packages.	22	5	1	27	> 95% lead coverage	5	MTAI	Standard Pb-free solderability is the requirement.
Backward Solderability	J-STD-002D ;Perform 8 hours steam aging for Matte tin finish and 1 hour steam aging for NiPdAu finish prior to testing.  Backward: Matte tin/ NiPdAu finish, SnPb solder, wetting temp 215°C for SMD.	22	5	1	27	> 95% lead coverage	5	MTAI	
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	1	5	0	5	CARC	30 bonds from a min. 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	1	5	0	5	CARC	30 bonds from a min. 5 devices.



Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	REL Test Site	Special Instructions
Physical Dimensions	Measure per JESD22 B100 and B108	10	0	3	30	0	5	CARC	
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5	CARC/MTAI	
Preconditioning - Required for surface mount devices	+150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type;  MSL1 @ 260C	231	15	3	738	0	15	MTAI	Spares should be properly identified. 77 parts from each lot to be used for HAST, uHAST, Temp Cycle test.
HAST	+130°C/85% RH for 96 hours  Electrical test pre and post stress at +25°C	77	5	3	246	0	10	MTAI	Spares should be properly identified.

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	REL Test Site	Special Instructions
UHASt	+130°C/85% RH for 96 hrs  Electrical test pre and post stress at +25°C	77	5	3	246	0	10	MTAI	Spares should be properly identified.
Temp Cycle	-65°C to +150°C for 500 cycles.  Electrical test pre and post stress at +25°C; 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress.	77	5	3	246	0	15	MTAI	Spares should be properly identified.

ALAN-28BFQE464 - CCB 5102 Initial Notice: Qualification of CARC as new assembly site for LX7167ACLD-TR and L

Affected Catalog Part Numbers(CPN)

LX7167ACLD-TR

LX7167CLD-TR